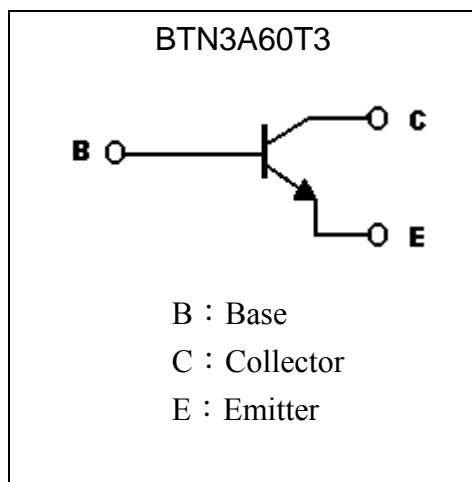
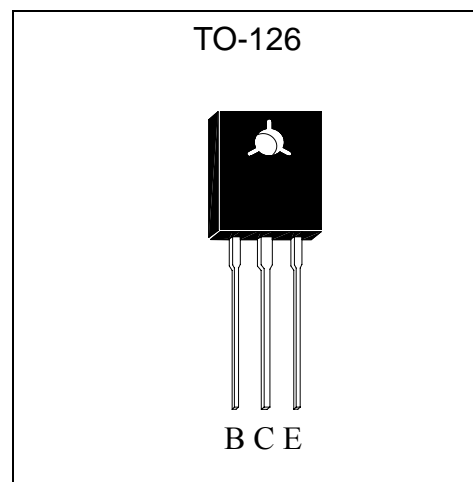


High Voltage NPN Triple Diffusion Planar Transistor

BTN3A60T3

Features

- High breakdown voltage. ($BV_{CEO}=700V$)
- High collector current capability ($I_{C(max)}=3A$)

Symbol

Outline

Absolute Maximum Ratings ($T_a=25^{\circ}C$)

Parameter	Symbol	Limit	Unit
Collector-Base Voltage	V_{CBO}	900	V
Collector-Emitter Voltage	V_{CEO}	700	V
Emitter-Base Voltage	V_{EBO}	9	V
Collector Current (DC)	I_C	3	A
Power Dissipation ($T_A=25^{\circ}C$)	P_D	1.2	W
Power Dissipation ($T_C=25^{\circ}C$)		40	
Junction Temperature	T_j	150	$^{\circ}C$
Storage Temperature	T_{stg}	-55~+150	$^{\circ}C$



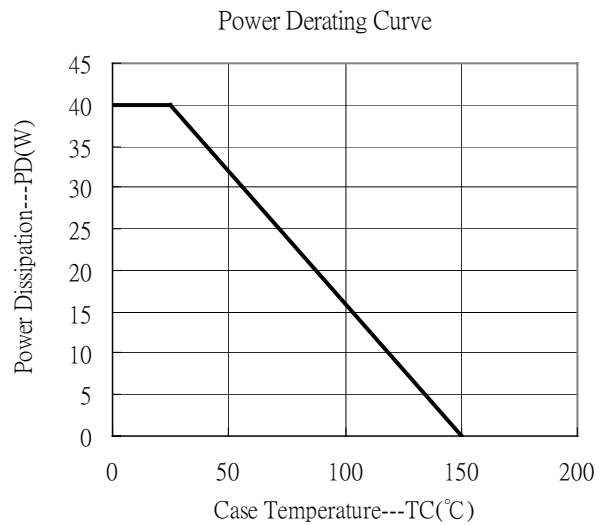
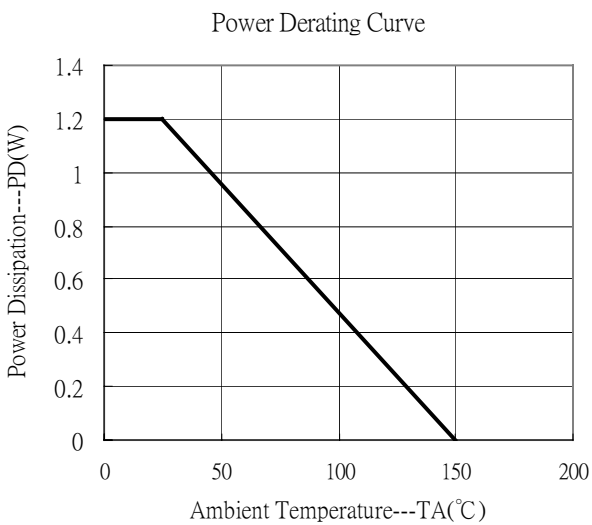
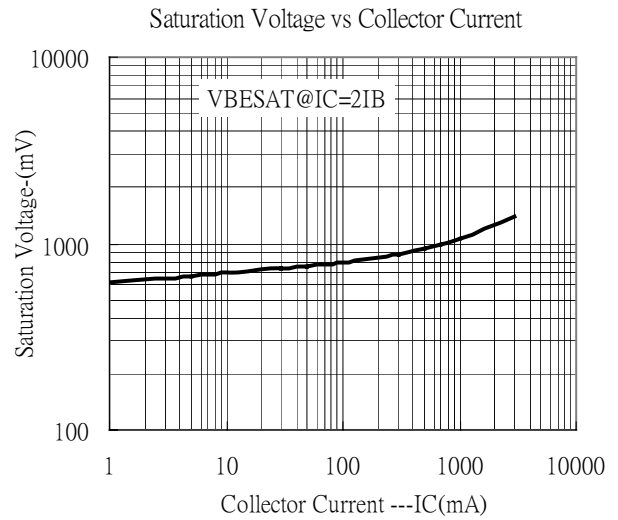
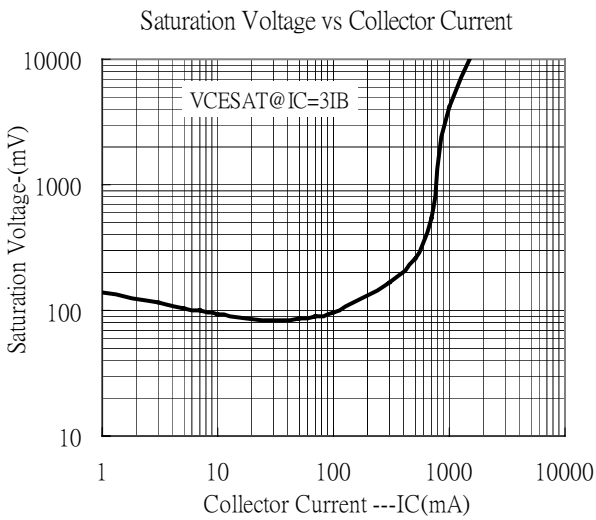
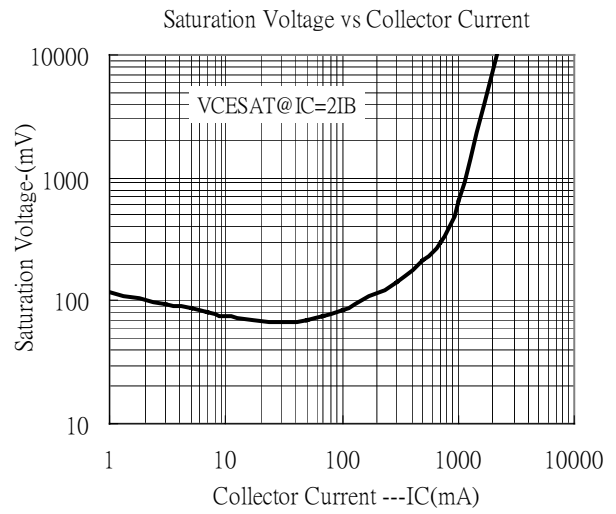
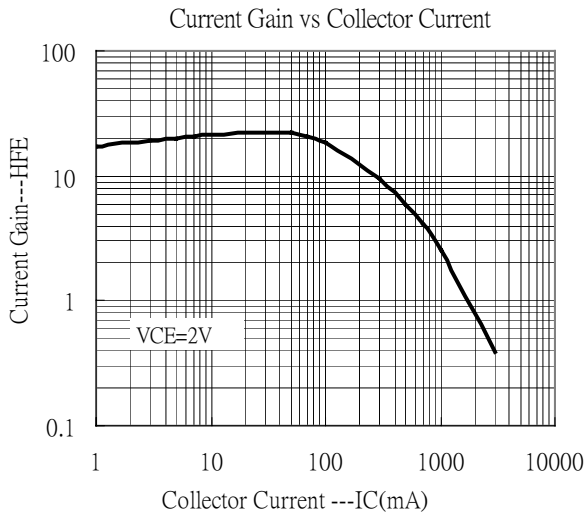
Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BV _{CB0}	900	-	-	V	I _C =50μA, I _E =0
BV _{CEO}	700	-	-	V	I _C =1mA, I _B =0
BV _{EBO}	9	-	-	V	I _E =50μA, I _C =0
I _{CEO}	-	-	10	μA	V _{CB} =700V, I _E =0
I _{CBO}	-	-	10	μA	V _{CB} =900V, I _E =0
I _{EBO}	-	-	10	μA	V _{EB} =7V, I _C =0
*V _{CE(sat)}	-	-	0.6	V	I _C =0.5A, I _B =0.25A
h _{FE}	10	-	40	-	V _{CE} =5V, I _C =0.2A
f _T	-	4	-	MHz	V _{CE} =10V, I _C =100mA, f=1MHz

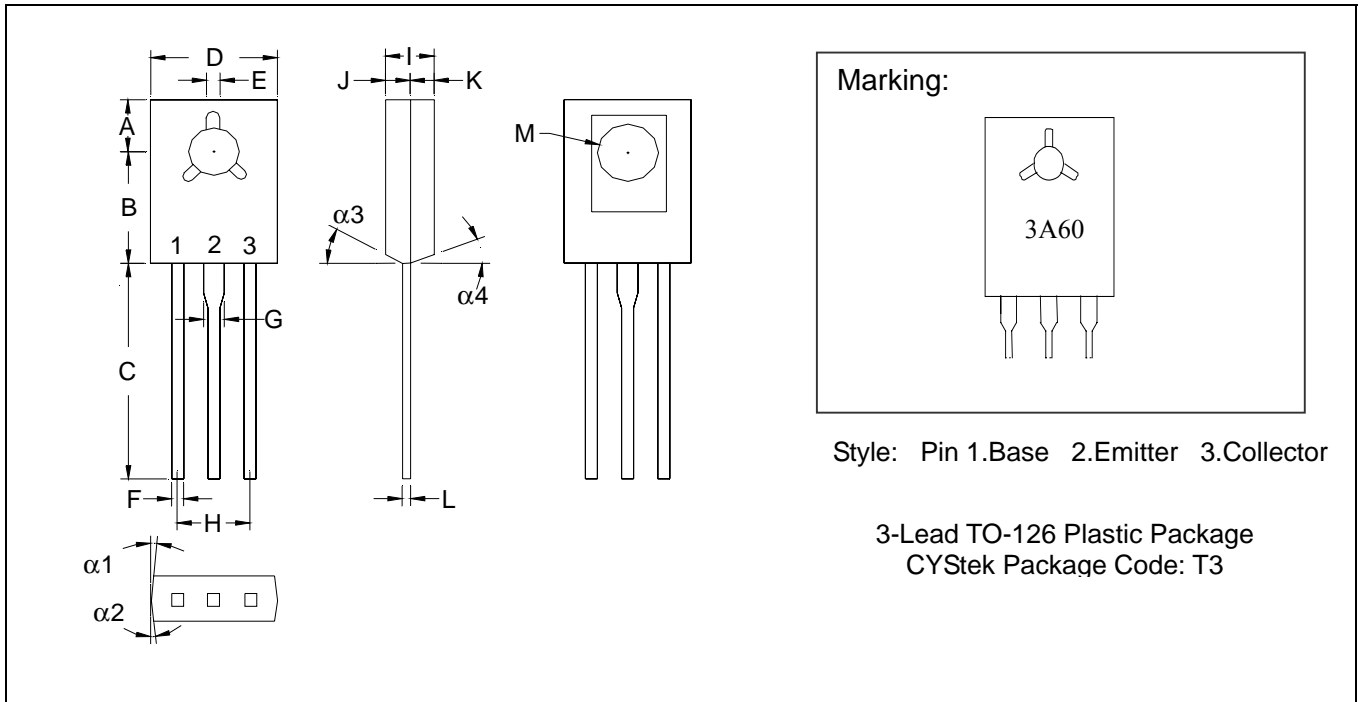
*Pulse Test : Pulse Width ≤380μs, Duty Cycle≤2%



Characteristic Curves



TO-126 Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
$\alpha 1$	-	*3°	-	*3°	F	0.0280	0.0319	0.71	0.81
$\alpha 2$	-	*3°	-	*3°	G	0.0480	0.0520	1.22	1.32
$\alpha 3$	-	*3°	-	*3°	H	0.1709	0.1890	4.34	4.80
$\alpha 4$	-	*3°	-	*3°	I	0.0950	0.1050	2.41	2.66
A	0.1500	0.1539	3.81	3.91	J	0.0450	0.0550	1.14	1.39
B	0.2752	0.2791	6.99	7.09	K	0.0450	0.0550	1.14	1.39
C	0.5315	0.6102	13.50	15.50	L	-	*0.0217	-	*0.55
D	0.2854	0.3039	7.52	7.72	M	0.1378	0.1520	3.50	3.86
E	0.0374	0.0413	0.95	1.05					

Notes: 1.Controlling dimension: millimeters.
 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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